

AGENDA

P-2.5 COMMITTEE FOR TANTALUM & NIOBIUM CAPACITORS

WEDNESDAY, MAY 18, 2005

2:00 to 4:00 PM

Chateau Sonesta, New Orleans. LA

1. COMMITTEE ORGANIZATION AND PROCEDURES
 - 1.1 Membership and attendance
 - 1.2 Review and approve agenda
 - 1.3 Approve minutes of last meeting ,San Diego, CA 2005
 - 1.4 Correspondence

2. OLD BUSINESS
 - 2.1 Reports
 - 2.1.1 Passive Component User's Group (U.1).....Mike Lauri
(Announcement of future meeting dates and locations)
 - 2.1.2 Government Specifications and Standards..... DSCC Representative
 - 2.2 Surface Mount Tantalum Capacitors
 - 2.1 Status: Standard (EIA-535BAAC), Low ESR (EIA-535BAAE) combine, update at working group.
 - 2.2.2 Discussion of new case sizes, ratings, or products....All Members
 - 2.2.2.1 Lead-frame less/face down termination molded specification?
 - 2.2.3 Discussion: inclusion or deletion of ratings charts from molded specs.
 - 2.3 Hazardous and recyclable material considerations for tantalum chips.
 - 2.4.1 Lead free solder topics - Tin Whiskers.....
 - 2.5 Tantalum Polymer spec - Review Ballot Responses, vote for approval.
 - 2.6 Discussion of moisture sensitivity tests for SMD solid and polymer tantalum
 - 2.6.1 Review existing specifications: J-Std-020C, IPC-5903 (MSL passives), IPC-5904 (Assembly Process Simulation for Non-IC Devices)
 - 2.7 Review and update EIA list of "active working projects"
 - 2.8 Review Niobium/NbO draft specification/ PN number 5075
 - 2.9 Update EIA IS 717 Qualification at working group meeting.

3. NEW BUSINESS
 - 3.1 Date Code Limitations in the industry for Tantalums
 - 3.1.5 Component Bulleting (Asia) for Tantalum Metal - Green
 - 3.2 Inputs for "All-Chairs Meeting"

4. ADJOURNMENT